

Part Number:			AS4C1G8D4-75BCN/BIN									
Part Weight(mg):			179.114									
NO.	Part Name	Material Name	Material Part no.	Material mass (mg)	Substance in Materials	CAS Number	Element wt (%)	wt% of Total unit wt	Substance Weight (mg)	PPM		
1	Substrate	Substrate_CCL	NPG-180INBK	27.0000	E-Glass Farbic	65997-17-3	40.000%	6.0297%	10.8000	400000		
					Epoxy Resin	29690-82-2	20.000%	3.0148%	5.4000	200000		
	Filler				14808-60-7	30.000%	4.5223%	8.1000	300000			
	Phosphorus Flame Restardant				35948-25-5	10.000%	1.5074%	2.7000	100000			
	Solder mask	AUS308 (PSR-4000/CA-40)	4.4625	Copper Foil	Copper foil	3.4595	Copper	7440-50-8	100.000%	1.9315%	3.4595	1000000
				Acrylic resin	Trade Secret	20.000%	0.4983%	0.8925	200000			
				Barium Sulfate	7727-43-7	10.350%	0.2579%	0.4619	103500			
				3-Methoxy-3-Methyl Butyl-Acetate	103429-90-9	10.000%	0.2491%	0.4463	100000			
				Dipropylene glycol monomethyl ether	34590-94-8	2.850%	0.0710%	0.1272	28500			
				Talc containing no asbestiform fibers	14807-96-6	0.350%	0.0087%	0.0156	3500			
				photopolymerization	Trade Secret	0.350%	0.0087%	0.0156	3500			
				Solvent naphtha	64742-94-5	0.350%	0.0087%	0.0156	3500			
				auxiliaries ; additives	Trade Secret	0.350%	0.0087%	0.0156	3500			
				SiO2 Compounds	Trade Secret	0.500%	0.0125%	0.0223	5000			
				Phthalocyanine Green G	Trade Secret	0.500%	0.0125%	0.0223	5000			
				organic pigments	Trade Secret	0.500%	0.0125%	0.0223	5000			
				Acrylic resin	Trade Secret	10.000%	0.2491%	0.4463	100000			
				Epoxy resins	Trade Secret	22.850%	0.5693%	1.0197	228500			
	organic fillers	Trade Secret	0.350%	0.0087%	0.0156	3500						
	Barium Sulfate	7727-43-7	10.350%	0.2579%	0.4619	103500						
Dipropylene glycol monomethyl ether	34590-94-8	10.000%	0.2491%	0.4463	100000							
3-Methoxy-3-Methyl Butyl-Acetate	103429-90-9	0.350%	0.0087%	0.0156	3500							
Copper Plating	Copper	17.2973	Copper	7440-50-8	100.000%	9.6571%	17.2973	1000000				
Nickel plating	Nickel	1.1836	Nickel	7440-02-0	100.000%	0.6608%	1.1836	1000000				
Gold Plating	Gold	0.1412	Gold	7440-57-5	100.000%	0.0788%	0.1412	1000000				
2	Compound	Resin	CEL-9120HF	59.1749	Epoxy resin	Trade secret	5.010%	1.6552%	2.9647	50100		
					Hardener	Trade secret	5.110%	1.6882%	3.0238	51100		
					Carbon black	1333-86-4	0.160%	0.0529%	0.0947	1600		
					Amorphous silica	60676-86-0	86.490%	28.5742%	51.1804	864900		
					Crystalline silica	14808-60-7	3.230%	1.0671%	1.9113	32300		
3	Die Adhesive	Epoxy	6202C	3.0400	2-(2-Ethoxyethoxy)ethyl acetate	112-15-2	36.500%	0.6195%	1.1096	365000		
					Butadiene, acrylonitrile polymer, carboxy-terminated, polymer with bisphenol A and epichlorohydrin	68610-41-3	28.000%	0.4752%	0.8512	280000		
					Isodecyl alcohol, ethoxylated	61827-42-7	10.000%	0.1697%	0.3040	100000		
					Silica Filler	112926-00-8	25.000%	0.4243%	0.7600	250000		
Tert-butyl peroxyneodecanoate	26748-41-4	0.500%	0.0085%	0.0152	5000							
4	Solder Ball	Metal	M705	27.5260	Tin	7440-31-5	96.500%	14.8300%	26.5626	965000		
					Silver	7440-22-4	3.000%	0.4610%	0.8258	30000		
					Copper	7440-50-8	0.500%	0.0768%	0.1376	5000		
5	Gold Wire	Metal	4N	0.2550	Gold	7440-57-5	100.000%	0.1424%	0.2550	1000000		
6	Chip	Silicon	20nm	35.5740	Silicon	7440-21-3	99.682%	19.7979%	35.4609	996820		
					Aluminum	7429-90-5	0.149%	0.0296%	0.0530	1490		
					Tungston	7440-33-7	0.106%	0.0211%	0.0377	1060		
					Titanium	7440-32-6	0.042%	0.0083%	0.0149	420		
					Boron	7440-42-8	0.006%	0.0012%	0.0021	60		
					Arsenic	7440-38-2	0.003%	0.0006%	0.0011	30		
					Phosphorous	7723-14-0	0.004%	0.0008%	0.0014	40		
					Copper	7440-50-8	0.005%	0.0010%	0.0018	50		
Fluorine	7782-41-4	0.003%	0.0006%	0.0011	30							
				179.1140				1100.000%	179.1140			